

PHOTOCOUPLER PS2761-1

HIGH ISOLATION VOLTAGE 4-PIN SOP PHOTOCOUPLER

-NEPOC Series-

DESCRIPTION

The PS2761-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon phototransistor.

This package is mounted in a plastic SOP (Small Outline Package) for high density applications.

The package has shield effect to cut off ambient light.

FEATURES

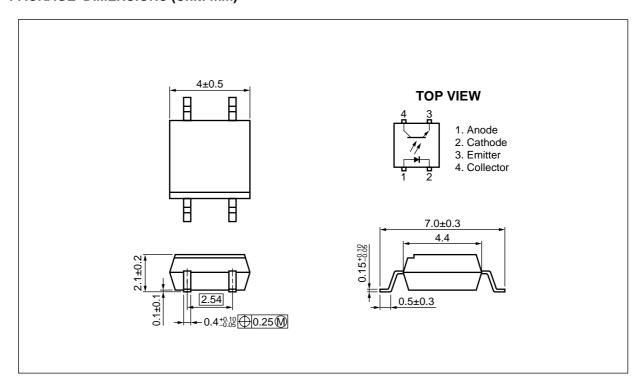
- Isolation distance (0.4 mm MIN.)
- High isolation voltage (BV = 3 750 Vr.m.s.)
- SOP (Small Outline Package) type
- High-speed switching ($t_r = 4 \mu s$ TYP., $t_f = 5 \mu s$ TYP.)
- Ordering number of taping product: PS2761-1-F3, F4
- UL approved: File No. E72422 (S)
- BSI approved: No. 8436/8437

APPLICATIONS

- Hybrid IC
- · Programmable logic controllers
- Power supply

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PACKAGE DIMENSIONS (Unit: mm)



PHOTOCOUPLER CONSTRUCTION

Parameter	Unit (MIN.)		
Air Distance	5 mm		
Creepage Distance	5 mm		
Isolation Distance	0.4 mm		



ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number*1
PS2761-1	4-pin SOP	Magazine case 100 pcs	PS2761-1
PS2761-1-F3		Embossed Tape 3 500 pcs/reel	
PS2761-1-F4			

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C, unless otherwise specified)

Parameter		Symbol Ratings		Unit
Diode	Forward Current (DC)	lF	50	mA
	Reverse Voltage	VR	6	V
	Power Dissipation Derating	∆P₀/°C	0.8	mW/°C
	Power Dissipation	Po	80	mW
	Peak Forward Current ^{*1}	I FP	1.0	Α
Transistor	Collector to Emitter Voltage	Vceo	40	V
	Emitter to Collector Voltage	Veco	5	V
	Collector Current	lc	40	mA
	Power Dissipation Derating	∆Pc/°C	1.5	mW/°C
	Power Dissipation	Pc	150	mW
Isolation Voltage ^{*2}		BV	3 750	Vr.m.s.
Operating Ambient Temperature		TA	-55 to +100	°C
Storage Temperature		Tstg	-55 to +150	°C

^{*1} PW = 100 μ s, Duty Cycle = 1 %

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^{*2} AC voltage for 1 minute at $T_A = 25$ °C, RH = 60 % between input and output



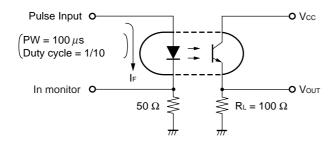
ELECTRICAL CHARACTERISTICS (TA = 25 °C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	I _F = 5 mA		1.1	1.4	V
	Reverse Current	I R	VR = 5 V			5	μΑ
	Terminal Capacitance	Ct	V = 0 V, f = 1 MHz		15		pF
Transistor	Collector to Emitter Dark Current	ICEO	IF = 0 mA, VcE = 40 V			100	nA
Coupled	Current Transfer Ratio	CTR	IF = 5 mA, VcE = 5 V	50	100	400	%
	Collector Saturation Voltage	VCE (sat)	IF = 10 mA, Ic = 2 mA			0.3	V
	Isolation Resistance	R _{I-O}	Vi-o = 1 kVDC	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		0.4		pF
	Rise Time ^{'2}	t r	Vcc = 5 V, $Ic = 2 mA$, $RL = 100 Ω$		4		μs
	Fall Time ^{'2}	tr			5		

*1 CTR rank

K: 200 to 400 (%) M: 50 to 150 (%) L: 100 to 300 (%) N: 50 to 400 (%)

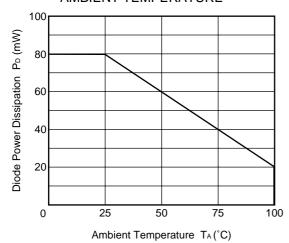
*2 Test circuit for switching time



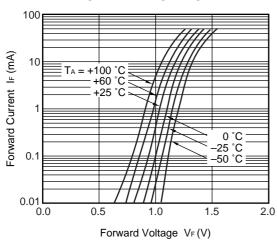


TYPICAL CHARACTERISTICS (TA = 25 °C, unless otherwise specified)

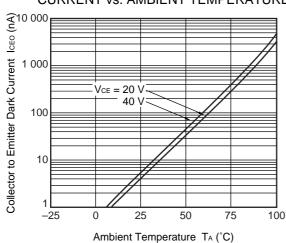
DIODE POWER DISSIPATION vs. AMBIENT TEMPERATURE



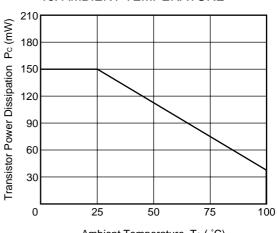
FORWARD CURRENT vs. FORWARD VOLTAGE



COLLECTOR TO EMITTER DARK CURRENT vs. AMBIENT TEMPERATURE

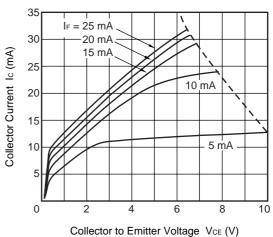


TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE

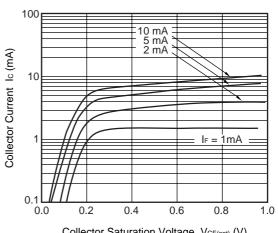


Ambient Temperature T_A (°C)

COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE

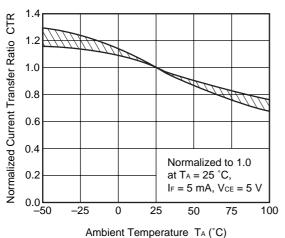


COLLECTOR CURRENT vs.
COLLECTOR SATURATION VOLTAGE

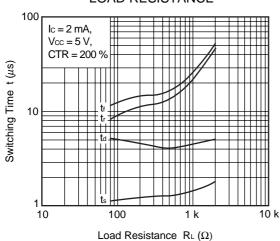


Collector Saturation Voltage $\ V_{CE(sat)}\ (V)$

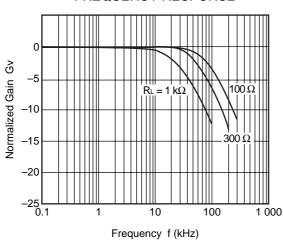
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



SWITCHING TIME vs. LOAD RESISTANCE

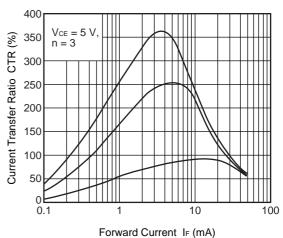


FREQUENCY RESPONSE

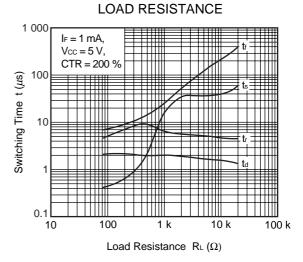


Remark The graphs indicate nominal characteristics.

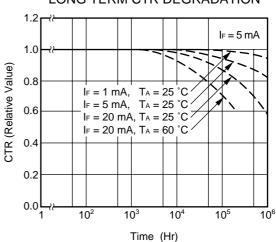
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



SWITCHING TIME vs.

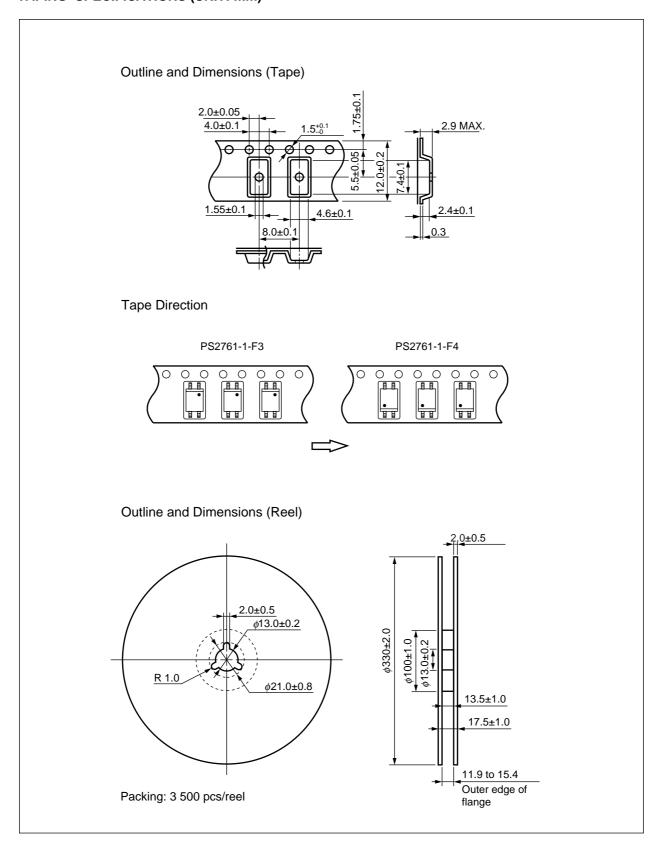


LONG TERM CTR DEGRADATION





* TAPING SPECIFICATIONS (UNIT: mm)



NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

Peak reflow temperature
 235 °C or below (package surface temperature)

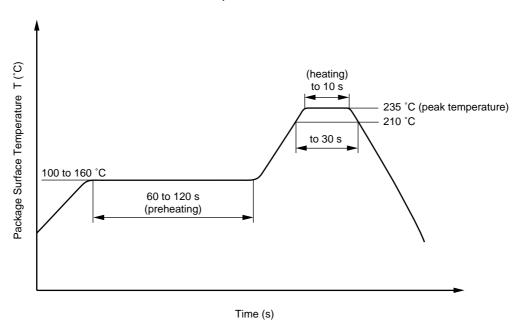
• Time of temperature higher than 210 °C 30 seconds or less

Number of reflows
 Three

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt % is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Dip soldering

• Temperature 260 °C or below (molten solder temperature)

• Time 10 seconds or less

Number of times
 One (Allowed to be dipped in solder including plastic mold portion.)

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of

0.2 Wt % is recommended.)

(3) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between corrector-emitters at startup, the output side may enter the on state, even if the voltage is within the absolute maximum ratings.

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SAFETY INFORMATION ON THIS PRODUCT

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GaAs Products

The product contains gallium arsenide, GaAs.

GaAs vapor and powder are hazardous to human health if inhaled or ingested.

- Do not destroy or burn the product.
- Do not cut or cleave off any part of the product.
- Do not crush or chemically dissolve the product.
- Do not put the product in the mouth.

Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

▶ For further information, please contact

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